

### **Power MOSFET Modules**

#### SKM 453A020

#### Features

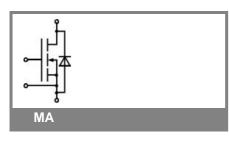
- N Channel, enhancement mode
- Avalanche characteristic
- Short internal connectionons
  avoid oscillations
- Isolated copper baseplate using Al<sub>2</sub>O<sub>3</sub> ceramic Direct Copper Bonding Technology (DCB)
- All electrical connections on top for easy busbaring
- Large clearances (12 mm) and creepage distances (20 mm)

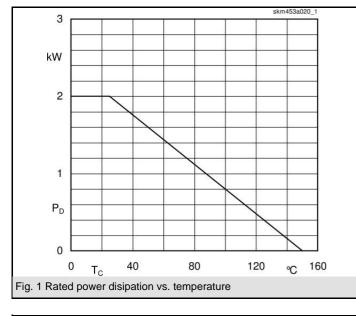
#### **Typical Applications**

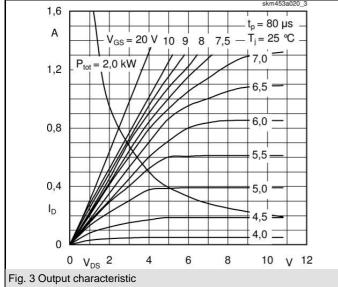
- DC servo and robot drives
- DC choppers
- UPS equipment
- Plasma cutting
- Not suitable for linear amplification

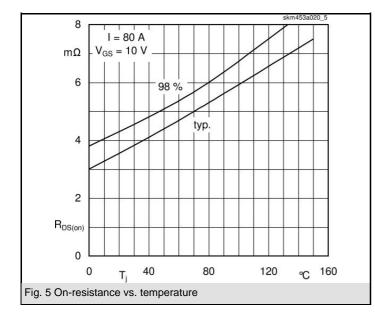
Absolute	Maximum Ratings	$T_c$ = 25 °C, unless otherwise specified					
Symbol	Conditions	Values	Units				
V <sub>DS</sub>		200	V				
I <sub>D</sub>	T <sub>s</sub> = 25 (80) °C	450 (400)	А				
I <sub>DM</sub>	1 ms	1350	А				
V <sub>GS</sub>		± 20	V				
T <sub>vj</sub> , (T <sub>stg</sub> )		- 40 +150 (125)	°C				
V <sub>isol</sub>	AC, 1 min.	2500	V				
Inverse diode							
I <sub>F</sub> = - I <sub>S</sub>		450	А				
$I_{FM}$ = - $I_{SM}$		1600	А				

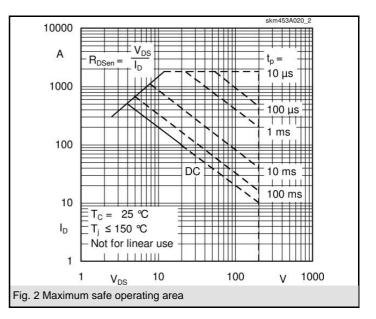
Characteristics		$T_c$ = 25 °C, unless otherwise specified					
Symbol	Conditions	min.	typ.	max.	Units		
V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 0,5 mA	200			V		
V <sub>GS(th)</sub>	$V_{GS} = V_{DS}, I_D = 1 \text{ mA}$	2,1	3	4	V		
I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 200 V, T <sub>i</sub> = 25 (125) °C			250 (2500)	μA		
I <sub>GSS</sub>	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V			100	nA		
R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 300 A		3,8	4,3	mΩ		
g <sub>fs</sub>	V <sub>DS</sub> = 25 V, I <sub>D</sub> = 300 A		400		S		
C <sub>CHC</sub>	V <sub>GS</sub> = 0, V <sub>DS</sub> = 25 V, f = 1 MHz		250		pF		
C <sub>iss</sub>			67	78	nF		
C <sub>oss</sub>			13	15	nF		
C <sub>rss</sub>			5	7	nF		
L <sub>DS</sub>				20 (60)	nH		
t <sub>d(on)</sub>	V <sub>DD</sub> = 30 V, I <sub>D</sub> = 300 A,		100		ns		
t,	$V_{GS}$ = = 10 V, $R_{G}$ = 2 $\Omega$		100		ns		
t <sub>d(off)</sub>			700		ns		
t <sub>f</sub>			250		ns		
Inverse diode							
V <sub>SD</sub>	I <sub>F</sub> = 600 A; V <sub>GS</sub> = 0 V			1,5	V		
t <sub>rr</sub>	T <sub>j</sub> = 25 (150) °C		160		ns		
Q <sub>rr</sub>	$T_j = 25 \ ^{\circ}C$		25		μC		
I <sub>rr</sub>	T <sub>j</sub> = 150 °C				A		
Thermal	Thermal characteristics						
R <sub>th(j-c)</sub>	per MOSFET			0,06	K/W		
R <sub>th(c-s)</sub>	${\sf M}_{\sf s},{\sf surface}$ , per module			0,038	K/W		
Mechanical data							
M <sub>s</sub>	to heatsink (M6)	3		5	Nm		
M <sub>t</sub>	for terminals (M5)	2,5		5	Nm		
w				325	g		

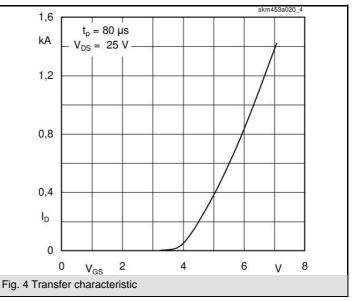


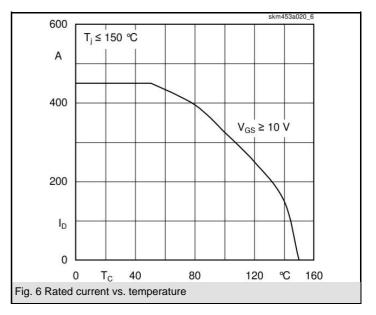


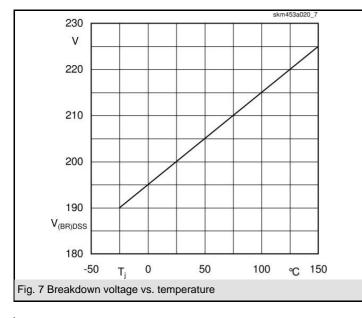


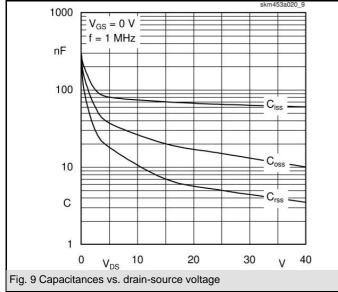


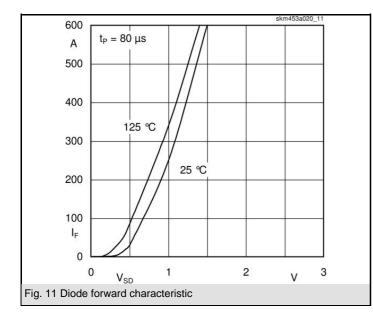


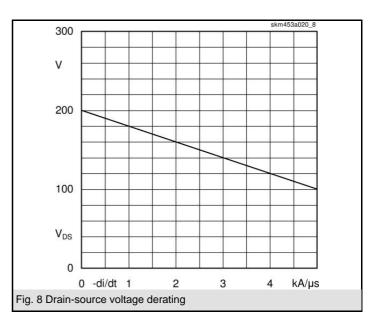


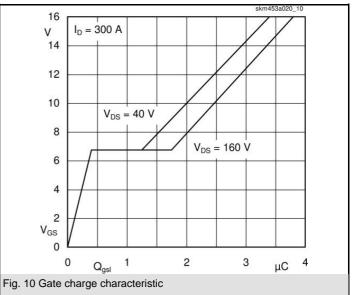


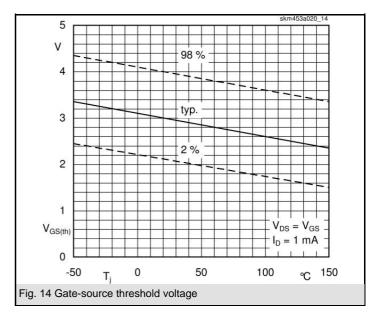


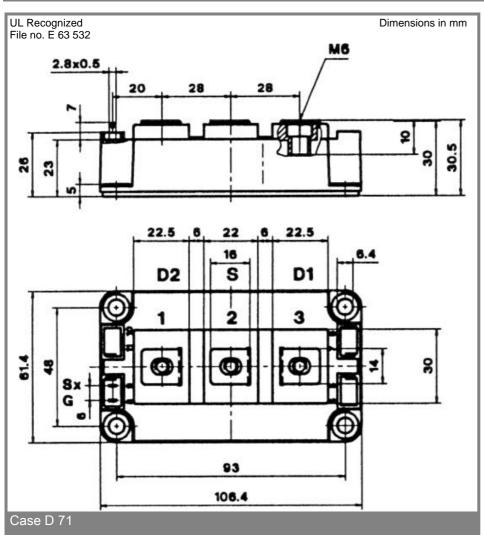


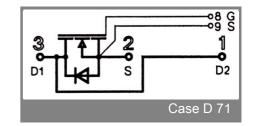












This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

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